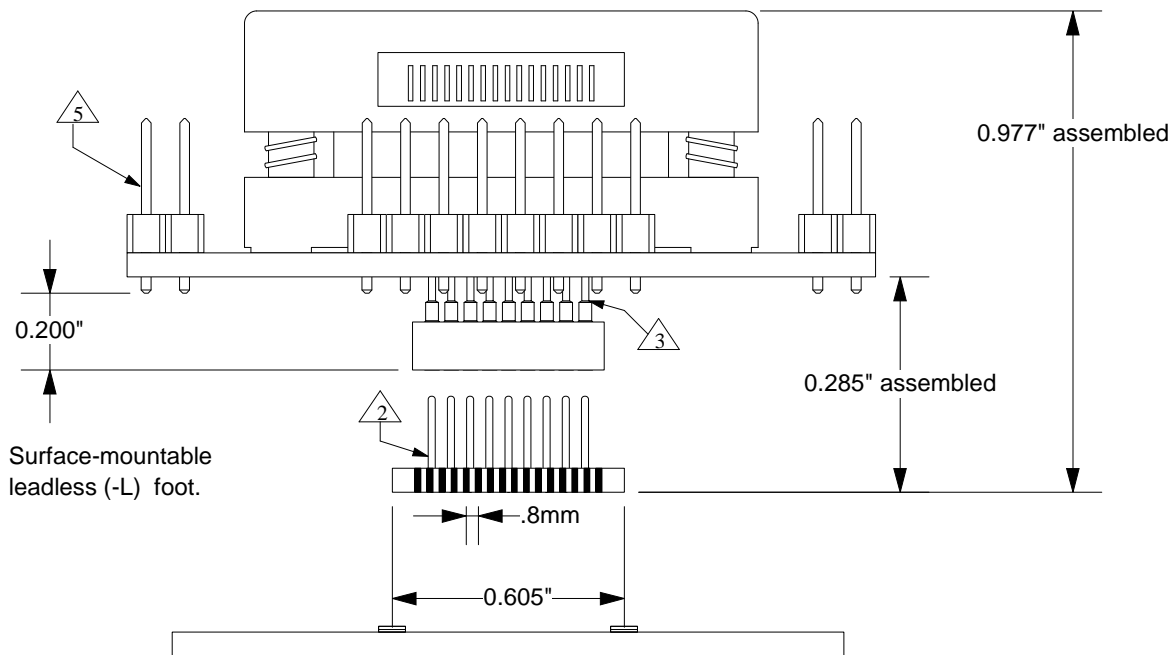



- △1 Substrate: 0.0625"±0.007" FR4/G10 or equivalent high temp material. 1/2 oz. Cu clad. SnPb plating
- △2 Pins: Material- Brass Alloy 360 1/2 hard; finish- 10µ" Au over 50µ" Ni (min.).
- △3 Pins: shell material- Brass Alloy 360 1/2 hard; finish- 10µ" Au over 50µ" Ni (min.). Contact material- BeCu; finish 10µ" Au over 100µ" Ni (min.)
- △5 Test points: material- Phosphor Bronze; plating- Sn over 50µ" Ni. Gold flash on contact end.



Description: Carrier Adaptor (QFE64SA Foot Print Spec)
 64 position (0.8 mm pitch) QFP Zero Insertion Force socket with test points to 64 position surface mountable QFP emulator foot. The 2 piece adaptor interconnects via gold plated (0.05" center) Mini-grid socket interface.
 All tolerances are ±0.005" unless otherwise specified. Materials and specifications are subject to change without notice.

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	Drawing: M Lund	Date: 12/15/95	File: CA-QFE064SA-L-Z-T-01 Dwg	Modified: 7/9/98